

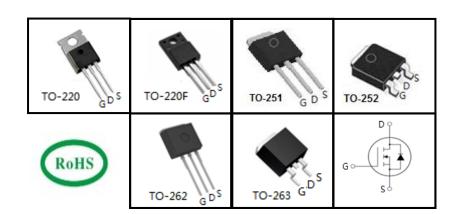
# **650V Super-Junction Power MOSFET**

#### **FEATURES**

- Very low FOM  $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information						
Device	TPP65R940C	TPA65R940C	TPU65R940C	TPD65R940C	TPC65R940C	TPB65R940C
Package	TO-220	TO-220F	TO-251	TO-252	TO-262	TO-263
Marking	65R940C	65R940C	65R940C	65R940C	65R940C	65R940C

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted					
Parameter	Comple of	Value		Unit	
Parameter	Symbol	TO-251, TO-252	TO-220F	Offic	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	650		V	
Continuous Drain Current	I <sub>D</sub>	4		Α	
Pulsed Drain Current (note1)	I <sub>DM</sub>	12		А	
Gate-Source Voltage	$V_{GSS}$	±30		V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	52.8		mJ	
Avalanche Current (note1)	I <sub>AR</sub>	0.8		А	
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	0.09		mJ	
Power Dissipation (T <sub>C</sub> = 25°C)	$P_{D}$	28 23		W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C	

Thermal Resistance						
Parameter	Symbol	Value		l lmit		
Parameter	Symbol	TO-251, TO-252	TO-220F	Unit		
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	4.4	5.5	°C/W		
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62	80	°C/VV		

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### TPP65R940C, TPA65R940C, TPU65R940C, TPD65R940C, TPC65R940C, TPB65R940C

## Wuxi Unigroup Microelectronics Company

<b>Specifications</b> T <sub>J</sub> = 25°C, ur	11633 01116	Twise Hoted				
Parameter	Symbol	Test Conditions		Value	1	Unit
			Min.	Тур.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	650			V
7 O-4 V-14 D	I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA
Zero Gate Voltage Drain Current		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1A		0.88	1.0	Ω
Forward Transconductance (Note3)	g <sub>fs</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1A		3		S
Dynamic						
Input Capacitance	C <sub>iss</sub>	\/ O\/		350		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 50V,$		20		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		2.6		
Total Gate Charge	$Q_g$			7		nC
Gate-Source Charge	$Q_gs$	$V_{DD} = 520V, I_{D} = 4A,$ $V_{GS} = 10V$		1.5		
Gate-Drain Charge	$Q_gd$	GS = 101		2.5		
Turn-on Delay Time	t <sub>d(on)</sub>			36		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 400V, I_{D} = 4A,$		27		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25\Omega$		79		
Turn-off Fall Time	t <sub>f</sub>			29		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I <sub>s</sub>	T 0500			3.9	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25°C			12	Α
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 4A$ , $V_{GS} = 0V$		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			220		ns
Reverse Recovery Charge	Q <sub>rr</sub>	$V_R = 480V, I_F = I_S,$ $di_F/dt = 100A/\mu s$		0.9		μC
Peak Reverse Recovery Current	I <sub>rrm</sub>			8		Α

#### **Notes**

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $I_{AS}$  = 0.8A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



### **Typical Characteristics** $T_J = 25^{\circ}$ C, unless otherwise noted

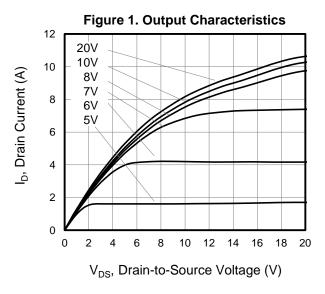


Figure 3. On-Resistance vs. Drain Current

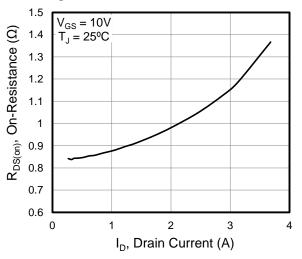


Figure 5. Gate Charge

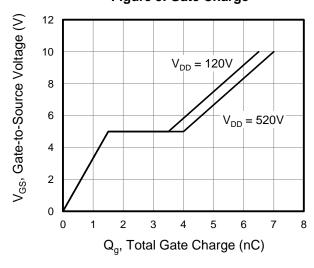


Figure 2. Transfer Characteristics

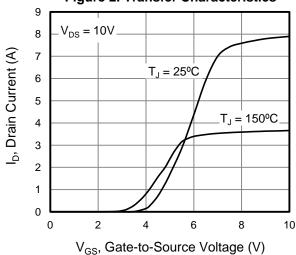


Figure 4. Capacitance

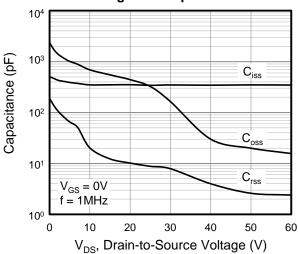
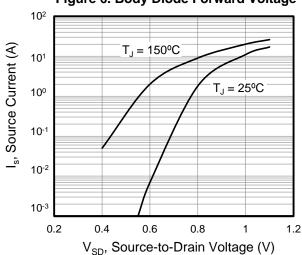


Figure 6. Body Diode Forward Voltage

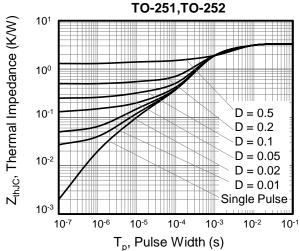




## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 7. On-Resistance vs. **Junction Temperature** 3  $V_{GS} = 10V$  $I_D = 2A$ R<sub>DS(on)</sub>, (Normalized) 2.5 1.5 1 0.5 0 0 -100 -50 50 100 150 200 T<sub>J</sub>, Junction Temperature (°C)

Figure 9. Transient Thermal Impedance



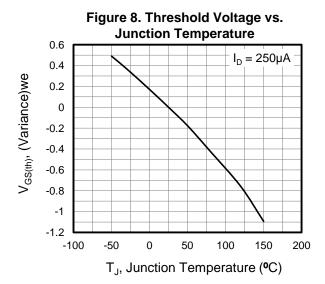
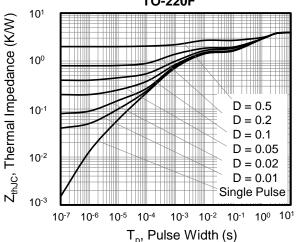


Figure 10. Transient Thermal Impedance TO-220F



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Figure A: Gate Charge Test Circuit and Waveform

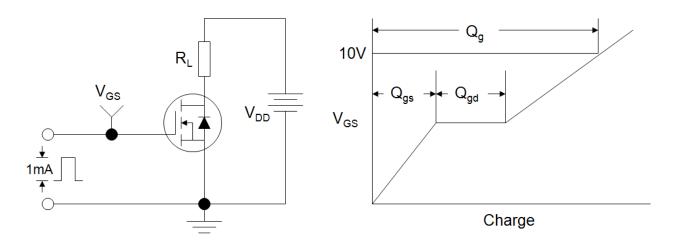


Figure B: Resistive Switching Test Circuit and Waveform

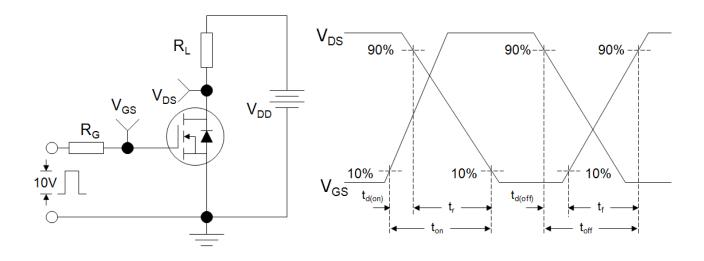
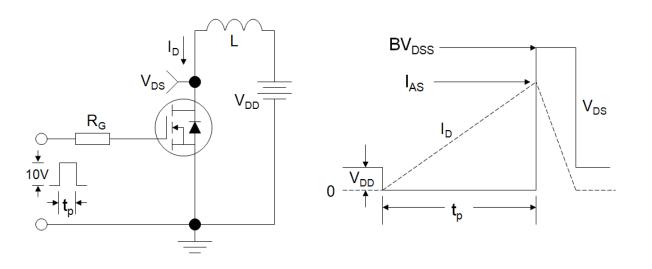
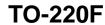


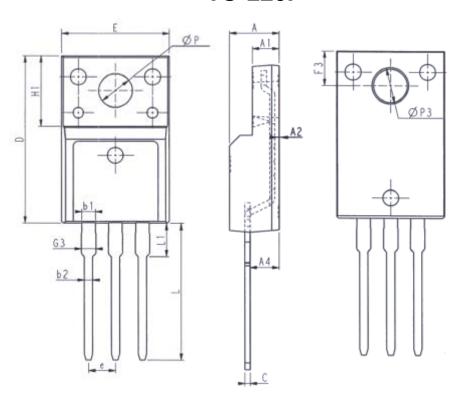
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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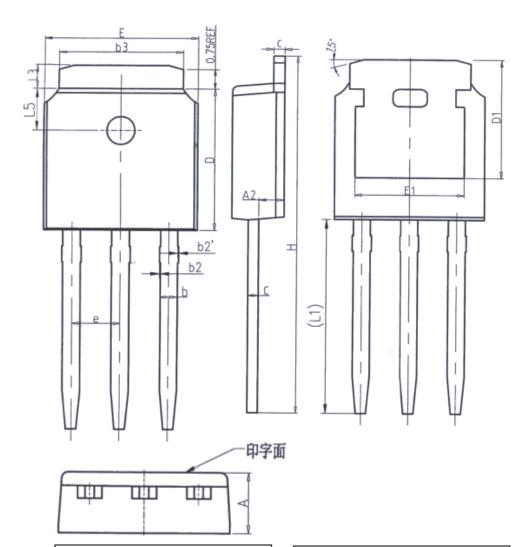




Unit: mm			Unit: mm			
Symbol	Min.	Max.	Symbol	Min.	Max.	
E	9. 96	10.36	L	12. 68	13. 28	
Α	4. 50	4. 90	L1	2. 93	3. 13	
A1	2. 34	2. 74	Р	3. 03	3. 38	
A2	0. 30	0. 60	Р3	3. 15	3. 65	
A4	2. 56	2. 96	F3	3. 15	3. 45	
С	0. 40	0. 65	G3	1. 25	1. 55	
D	15. 57	16. 17	b1	1. 18	1. 43	
H1	6. 70REF		b2	0. 70	0. 95	
е	2. 54BSC					



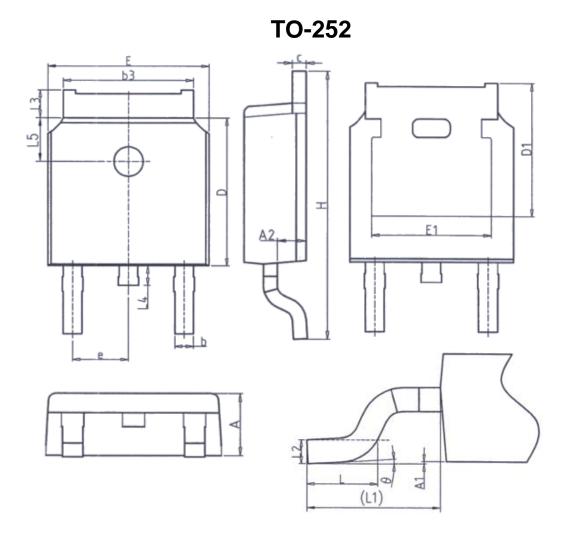
# **TO-251**



Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b2	0.00	0.10	
b2′	0.00	0.10	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	

Unit: mm				
Symbol	Min.	Max.		
D1	5. 30	REF		
E	6. 40	6. 80		
E1	4. 63	-		
е	2. 286BSC			
Н	16. 22	16. 82		
L1	9. 15	9. 65		
L3	0.88	1. 28		
L5	1. 65	1. 95		





Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	_		

Unit: mm				
Symbol	Min. Max.			
е	2. 286BSC			
Н	9. 40	10.50		
L	1. 38	1. 75		
L1	L1 2. 90REF			
L2	0. 51BSC			
L3	0.88	1. 28		
L4	_	1.00		
L5	1. 65	1. 95		
θ	0°	8°		



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